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## FDC610PZ P-Channel PowerTrench<sup>®</sup> MOSFET **–30V, –4.9A, 42m**Ω **Features**

- Max  $r_{DS(on)}$  = 42m $\Omega$  at V<sub>GS</sub> = -10V, I<sub>D</sub> = -4.9A
- Max  $r_{DS(on)}$  = 75m $\Omega$  at V<sub>GS</sub> = -4.5V, I<sub>D</sub> = -3.7A
- Low gate charge (17nC typical).
- High performance trench technology for extremely low r<sub>DS(on)</sub>.
- SuperSOT<sup>TM</sup> –6 package: small footprint (72% smaller than standard SO-8) low profile (1mm thick).
- RoHS Compliant

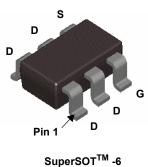


## **General Description**

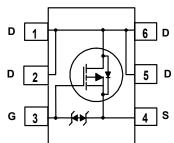
This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance. These devices are well suited for battery power applications: load switching and power management, battery charging circuits, and DC/DC conversion.

## Application

DC - DC Conversion







## MOSFET Maximum Ratings TA= 25°C unless otherwise noted

Symbol	mbol Parameter		Ratings	Units	
V <sub>DS</sub>	Drain to Source Voltage		-30	V	
V <sub>GS</sub>	Gate to Source Voltage		±25	V	
1	Drain Current -Continuous	(Note 1a)	-4.9	^	
D	-Pulsed		-20	Α	
D	Power Dissipation (Note 1a)		1.6	14/	
P <sub>D</sub>	Power Dissipation	(Note 1b)	0.8	W	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +150	°C	

## **Thermal Characteristics**

$R_{ hetaJA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	156	C/VV

## Package Marking and Ordering Information

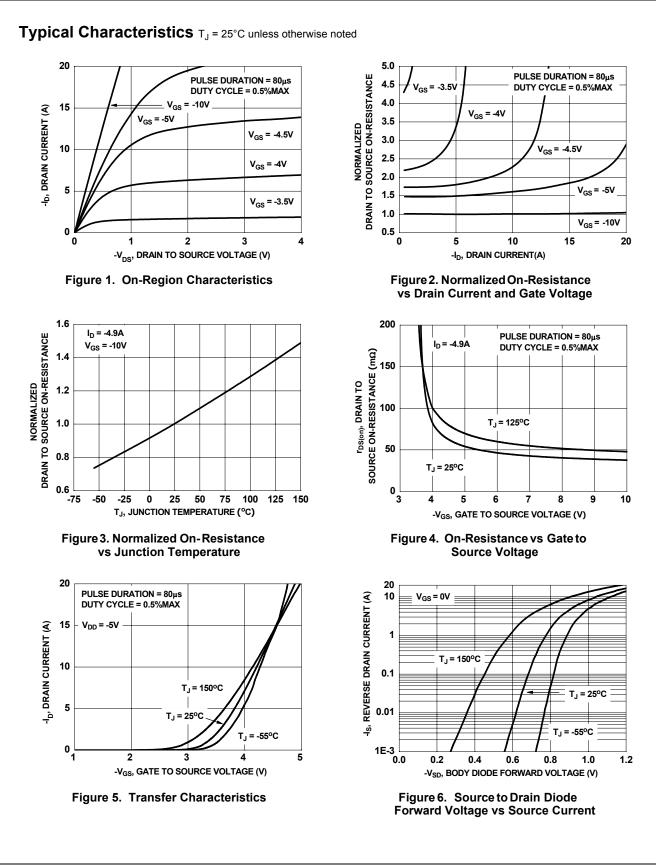
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.610Z	FDC610PZ	SSOT6	7"	8mm	3000units

August 2007

GaseGate to Source Leakage Current $V_{GS} = \pm 25V$ , $V_{DS} = 0V$ $\pm 10$ $\mu A$ On Characteristics $V_{GS(th)}$ Gate to Source Threshold Voltage Temperature Coefficient $V_{GS} = V_{DS}$ , $I_D = -250\mu A$ , referenced to $25^{\circ}C$ 6 $mV/^{\rho_1}$ $DS(on)$ Gate to Source On Resistance $V_{GS} = -10V$ , $I_D = -4.9A$ 3642 $mV/^{\rho_1}$ $DS(on)$ Static Drain to Source On Resistance $V_{GS} = -10V$ , $I_D = -4.9A$ 3642 $mQ/^{\rho_1}$ $PS(on)$ Static Drain to Source On Resistance $V_{GS} = -10V$ , $I_D = -4.9A$ , $T_J = 125^{\circ}C$ 5060 $V_{CS}$ Forward Transconductance $V_{DD} = -10V$ , $I_D = -4.9A$ 15S <b>bynamic Characteristics</b> $V_{DS} = -15V$ , $V_{GS} = 0V$ , $f = 1MHz$ 7551005 $pF$ $C_{SS}$ Reverse Transfer Capacitance $f = 1MHz$ 13 $\Omega$ $C_{SS}$ Gate Resistance $f = 1MHz$ 13 $\Omega$ $M_{CS}$ Turn-On Delay Time $r$ $Rise Time$ $\gamma$ 14ns $C_{MS}$ Total Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$ , $I_D = -4.9A$ 410ns $C_{MS}$ Total Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$ , $I_D = -4.9A$ 2.9nC $Q_{gd}$ Total Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$ , $I_D = -4.9A$ 2.9nC $Q_{gd}$ Gate to Source Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$ , $I_D = -4.9A$ 2.9nC $Q_{gd}$ Gate to Charge <td< th=""><th>Symbol</th><th>Parameter</th><th>Test Conditions</th><th>Min</th><th>Тур</th><th>Мах</th><th>Units</th></td<>	Symbol	Parameter	Test Conditions	Min	Тур	Мах	Units
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$\begin{array}{c c c c c c c c c c c c c c c c c c c $							
GaseGate to Source Leakage Current $V_{GS} = \pm 25V$ , $V_{DS} = 0V$ $\pm 10$ $\mu A$ On Characteristics $V_{GS(th)}$ Gate to Source Threshold Voltage Temperature Coefficient $V_{GS} = V_{DS}$ , $I_D = -250\mu A$ , referenced to $25^{\circ}C$ 6 $mV/^{\rho_1}$ $DS(on)$ Gate to Source On Resistance $V_{GS} = -10V$ , $I_D = -4.9A$ 3642 $mV/^{\rho_1}$ $DS(on)$ Static Drain to Source On Resistance $V_{GS} = -10V$ , $I_D = -4.9A$ 3642 $mQ/^{\rho_1}$ $PS(on)$ Static Drain to Source On Resistance $V_{GS} = -10V$ , $I_D = -4.9A$ , $T_J = 125^{\circ}C$ 5060 $V_{CS}$ Forward Transconductance $V_{DD} = -10V$ , $I_D = -4.9A$ 15S <b>bynamic Characteristics</b> $V_{DS} = -15V$ , $V_{GS} = 0V$ , $f = 1MHz$ 7551005 $pF$ $C_{SS}$ Reverse Transfer Capacitance $f = 1MHz$ 13 $\Omega$ $C_{SS}$ Gate Resistance $f = 1MHz$ 13 $\Omega$ $M_{CS}$ Turn-On Delay Time $r$ $Rise Time$ $\gamma$ 14ns $C_{MS}$ Total Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$ , $I_D = -4.9A$ 410ns $C_{MS}$ Total Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$ , $I_D = -4.9A$ 2.9nC $Q_{gd}$ Total Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$ , $I_D = -4.9A$ 2.9nC $Q_{gd}$ Gate to Source Gate Charge $V_{GS} = 0V$ to $-10V$ $V_{DD} = -15V$ , $I_D = -4.9A$ 2.9nC $Q_{gd}$ Gate to Charge <td< td=""><td></td><td></td><td><math>I_D = -250 \mu A</math>, referenced to 25°C</td><td></td><td>-22</td><td></td><td>mV/°C</td></td<>			$I_D = -250 \mu A$ , referenced to 25°C		-22		mV/°C
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	I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS}$ = ±25V, $V_{DS}$ = 0V			±10	μA
	On Chara	cteristics					
$ \begin{array}{c c c c c c c c c } \hline AT_J & Gate to Source Threshold Voltage Temperature Coefficient & I_D = -250 \mu A, referenced to 25°C & 6 & mV/^{\circ} \\ \hline AT_J & D_D & D_D$			$V_{00} = V_{00}$ $I_0 = -250 \mu \Delta$	_1	_22	_3	V
$\begin{array}{c c c c c c c c c c c c c c c c c c c $				-1	-2.2	-5	
		•	$I_D = -250 \mu A$ , referenced to 25°C		6		mV/°C
V <sub>GS</sub> = -10V, I <sub>D</sub> = -4.9A, T <sub>J</sub> = 125°C         50         60           HFS         Forward Transconductance         V <sub>DD</sub> = -10V, I <sub>D</sub> = -4.9A         15         S           Dynamic Characteristics         Input Capacitance         V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1MHz         145         195         pF           Coss         Output Capacitance         V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1MHz         145         195         pF           Crass         Reverse Transfer Capacitance         f = 1MHz         13         Ω         Ω           Cost         Gate Resistance         f = 1MHz         13         Ω         Ω           Writching Characteristics         f = 1MHz         13         Ω         Ω           d(on)         Turn-On Delay Time r         V <sub>DD</sub> = -15V, I <sub>D</sub> = -4.9A         4         10         ns           r         Rise Time         Q <sub>GS</sub> = 0V to -10V         V <sub>GS</sub> = 0V to -10V         33         53         ns           Q <sub>g</sub> Total Gate Charge         V <sub>GS</sub> = 0V to -4.5V         V <sub>DD</sub> = -4.9A         2.9         nC           Q <sub>g</sub> Total Gate Charge         V <sub>GS</sub> = 0V to -4.5V         V <sub>DD</sub> = -15V, I <sub>D</sub> = -4.9A         2.9         nC           Q <sub>g</sub> Total Gate Charge         V <sub>GS</sub> = 0V to -4.5V         V <sub>DD</sub> =		· · ·	$V_{GS} = -10V, I_{D} = -4.9A$		36	42	
Input Capacitance $V_{DD} = -10V, I_D = -4.9A$ 15SOpnamic Characteristics $V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$ 7551005pFCossOutput Capacitance $V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$ 145195pFCrssReverse Transfer Capacitancef = 1MHz13 $\Omega$ RgGate Resistancef = 1MHz13 $\Omega$ Switching Characteristics $V_{DD} = -15V, I_D = -4.9A$ $\gamma$ 144nsd(on)Turn-On Delay Time $V_{DD} = -15V, I_D = -4.9A$ $4$ 10nsfFall Time $V_{GS} = 0V to -10V$ $V_{GS} = 0V to -10V$ $V_{DD} = -15V, I_D = -4.9A$ $4$ 10ns $Q_g$ Total Gate Charge $V_{GS} = 0V to -10V$ $V_{DD} = -15V, I_D = -4.9A$ $4$ 10ns $Q_g$ Total Gate Charge $V_{GS} = 0V to -10V$ $V_{DD} = -15V, I_D = -4.9A$ $177$ 24nC $Q_g$ Total Gate Charge $V_{GS} = 0V to -4.5V$ $V_{DD} = -15V, I_D = -4.9A$ $2.9$ nC $Q_{gd}$ Gate to Drain "Miller" Charge $I_D = -4.9A$ $2.9$ nC $D_{gd}$ Gate to Drain "Miller" Charge $I_D = -4.9A$ $2.9$ nC $D_{gd}$ Gate to Drain "Miller" Charge $I_D = -4.9A$ <td>r<sub>DS(on)</sub></td> <td>Static Drain to Source On Resistance</td> <td><math>V_{GS} = -4.5V, I_D = -3.7A</math></td> <td></td> <td>58</td> <td>75</td> <td>mΩ</td>	r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = -4.5V, I_D = -3.7A$		58	75	mΩ
Dynamic CharacteristicsCissInput Capacitance $V_{DS} = -15V, V_{GS} = 0V,$ 7551005pFCossOutput Capacitance $f = 1MHz$ 145195pFCrssReverse Transfer Capacitance $f = 1MHz$ 13 $\Omega$ CrssReverse Transfer Capacitance $f = 1MHz$ 13 $\Omega$ CrssReverse Transfer Capacitance $f = 1MHz$ 13 $\Omega$ CrssReverse Transfer Capacitance $f = 1MHz$ 13 $\Omega$ RgGate Resistance $f = 1MHz$ 13 $\Omega$ Switching Characteristics $V_{DD} = -15V, I_D = -4.9A$ $4$ 10ns $d_{doff}$ Turn-On Delay Time $V_{GS} = -10V, R_{GEN} = 6\Omega$ $33$ 53ns $f_{af}$ Fall Time $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V, I_D = -4.9A$ $4$ 10ns $\Omega_{g}$ Total Gate Charge $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V, I_D = -4.9A$ $2.9$ nc $\Omega_{gs}$ Gate to Source Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V, I_D = -4.9A$ $2.9$ nc $\Omega_{gs}$ Gate to Drain "Miller" Charge $I_D = -4.9A$ $2.9$ nc $\Omega_{gd}$ Gate to Drain "Miller" Charge $I_D = -4.9A$ $2.9$ ncDrain-Source Diode Characteristics			$V_{GS} = -10V, I_D = -4.9A, T_J = 125^{\circ}C$		50	60	
$\begin{array}{c c c c c c c c c c c c c c c c c c c $	9 <sub>FS</sub>	Forward Transconductance			15		S
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CossOutput Capacitance $V_{DS} = -15V$ , $V_{GS} = 0V$ , f = 1MHz145195pF $C_{rss}$ Reverse Transfer Capacitancef = 1MHz125190pF $R_g$ Gate Resistancef = 1MHz13 $\Omega$ Switching Characteristics $d(on)$ Turn-On Delay Time r $V_{DD} = -15V$ , $I_D = -4.9A$ $V_{GS} = -10V$ , $R_{GEN} = 6\Omega$ $q$ $q$ $M_{Cff}$ Turn-Off Delay Time r $V_{DD} = -15V$ , $I_D = -4.9A$ $V_{GS} = -10V$ , $R_{GEN} = 6\Omega$ $q$ $q$ $R_{g}$ Total Gate Charge $Q_{g}$ $V_{GS} = 0V$ to $-10V$ $V_{GS} = 0V$ to $-4.5V$ $V_{DD} = -15V$ , $I_D = -4.9A$ $q$ $q$ $Q_{g}$ Total Gate Charge $Q_{g}$ $V_{GS} = 0V$ to $-4.5V$ $V_{DD} = -15V$ , $I_D = -4.9A$ $q$ $q$ $Q_{g}$ Gate to Source Gate Charge $Q_{gd}$ $Q_{gs} = 0V$ to $-4.5V$ $V_{DD} = -15V$ , $I_D = -4.9A$ $q$ $q$ $Q_{gd}$ Gate to Drain "Miller" Charge $V_{GS} = 0V$ to $-4.5V$ $V_{DD} = -15V$ , $I_D = -4.9A$ $q$ $q$ $Q_{gd}$ Gate to Drain "Miller" Charge $Q$ $Q$ $Q$ $Q$ $Q$ $Q_{gd}$ Gate to Drain "Miller" Charge $Q$ $Q$ $Q$ $Q$ $Q_{gd}$ $Q$	-			1	755	1005	۳E
Social CrassReverse Transfer CapacitanceT = TMHZ125190pF $R_g$ Gate Resistancef = 1MHz13 $\Omega$ <b>Switching Characteristics</b> $d(on)$ Turn-On Delay Time $f = 1MHz$ 13 $\Omega$ $r_{r}$ Rise Time $V_{DD} = -15V, I_D = -4.9A$ $4$ 10ns $r_{d}$ Rise Time $V_{GS} = -10V, R_{GEN} = 6\Omega$ $33$ $53$ ns $r_{g}$ Total Gate Charge $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V, I_D = -4.9A$ $17$ $24$ nC $R_{g}$ Total Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V, I_D = -4.9A$ $17$ $24$ nC $R_{g}$ Total Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V, I_D = -4.9A$ $17$ $24$ nC $R_{g}$ Gate to Source Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V, I_D = -4.9A$ $2.9$ nC $R_{g}$ Gate to Drain "Miller" Charge $I_D = -4.9A$ $2.9$ nC $R_{g}$ Gate to Drain "Miller" Charge $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ $R_{g}$ Gate to Drain "Miller" Charge $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ $R_{g}$ Gate to Drain "Miller" Charge $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ $R_{g}$ Gate to Drain "Miller" Charge $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ $R_{g}$ $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$ $R_{g}$ $I_D = -4.9A$ $I_D = -4.9A$ $I_D = -4.9A$			$V_{DS} = -15V, V_{GS} = 0V,$				
$\begin{array}{c c c c c c c c c c c c c c c c c c c $			f = 1MHz		-		
gd(on)Turn-On Delay Time $V_{DD} = -15V, I_D = -4.9A$ $7$ 14nsrRise Time $V_{GS} = -10V, R_{GEN} = 6\Omega$ $33$ 53nsd(off)Turn-Off Delay Time $V_{GS} = -10V, R_{GEN} = 6\Omega$ $33$ $53$ ns $Q_g$ Total Gate Charge $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V, I_D = -4.9A$ $17$ $24$ nc $Q_g$ Total Gate Charge $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V, I_D = -4.9A$ $17$ $24$ nC $Q_g$ Total Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V, I_D = -4.9A$ $2.9$ $nC$ $Q_{gd}$ Gate to Source Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -4.9A$ $2.9$ $nC$ $D_{gd}$ Gate to Drain "Miller" Charge $4.3$ $nC$ Orain-Source Diode Characteristics		•	f - 1MU7		-	190	
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Rise Time $V_{DD} = -15V$ , $I_D = -4.9A$ 410ns $d_{(off)}$ Turn-Off Delay Time $V_{GS} = -10V$ , $R_{GEN} = 6\Omega$ 3353ns $f_f$ Fall Time2337ns $Q_g$ Total Gate Charge $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V$ ,1724nC $Q_g$ Total Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V$ ,913nC $Q_{gs}$ Gate to Source Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -4.9A$ 2.9nC $Q_{gd}$ Gate to Drain "Miller" Charge4.3nC0Orain-Source Diode Characteristics	Switching	g Characteristics					
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d(off)Turn-Off Delay Time3353ns $f$ Fall Time2337ns $Q_g$ Total Gate Charge $V_{GS} = 0V \text{ to } -10V$ $V_{DD} = -15V$ ,1724nC $Q_g$ Total Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V$ ,913nC $Q_{gd}$ Gate to Source Gate Charge $I_D = -4.9A$ 2.9nC $Q_{gd}$ Gate to Drain "Miller" Charge4.3nCOrain-Source Diode Characteristics	t <sub>r</sub>	Rise Time			4	10	ns
$Q_g$ Total Gate Charge $V_{GS} = 0V \text{ to } -10V$ 1724nC $Q_g$ Total Gate Charge $V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -15V$ ,913nC $Q_{gs}$ Gate to Source Gate Charge $I_D = -4.9A$ 2.9nC $Q_{gd}$ Gate to Drain "Miller" Charge4.3nCOrain-Source Diode Characteristics	t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = -10V, R_{GEN} = 602$		33	53	ns
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Q <sub>gd</sub> Gate to Drain "Miller" Charge     4.3     nC       Orain-Source Diode Characteristics	Qg	Total Gate Charge			17	24	nC
Q <sub>gd</sub> Gate to Drain "Miller" Charge     4.3     nC       Orain-Source Diode Characteristics	Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } -4.5V  V_{DD} = -15V,$		9	13	nC
Drain-Source Diode Characteristics	Q <sub>gs</sub>	Gate to Source Gate Charge	I <sub>D</sub> = -4.9A		2.9		nC
	Q <sub>gd</sub>	Gate to Drain "Miller" Charge			4.3		nC
	Drain-Sou	urco Diodo Charactoristics					
2 Maximum Continuous Drain-Source Diode Forward Current			de Ferryard Ourreat		1	4.0	•
					0.0		
			$V_{GS} = 0V, I_{S} = -1.5A$ (Note 2)				-
			– I <sub>F</sub> = –4.9A, di/dt = 100A/μs				
rr Reverse Recovery Time $I_{\rm E} = -4.9$ A, di/dt = 100A/us 19 35 ns		Reverse Recovery Charge			9	10	lic
	Q <sub>gs</sub> Q <sub>gd</sub>	Gate to Source Gate Charge Gate to Drain "Miller" Charge urce Diode Characteristics Maximum Continuous Drain-Source Dic Source to Drain Diode Forward Voltage	bde Forward Current $V_{GS} = 0V, I_S = -1.3A$ (Note 2)		2.9 4.3 -0.8	-1.3 -1.2	
SD contract or brain product or ward voltage $v_{GS} = vv$ , $v_{GS} = 1.3A$ (NULE 2) $-0.0$ $-1.2$ V	rr		I <sub>E</sub> = -4.9A, di/dt = 100A/us				
rr Reverse Recovery Time $I_{\rm E} = -4.9$ A, di/dt = 100A/us 19 35 ns	Q <sub>rr</sub>	Reverse Recovery Charge			9	18	nC
$\frac{19}{18} = -4.9A, di/dt = 100A/\mu s$	. $R_{\theta JA}$ is determ	nined with the device mounted on a 1in <sup>2</sup> pad 2 oz coppe	r pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{ m R,IC}$ is	guaranteed I	by design wh	ile R <sub>0CA</sub> is de	etermined
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	the user's boa	ird design.					
rrReverse Recovery TimeIF = -4.9A, di/dt = 100A/ $\mu$ s1935ns $Q_{rr}$ Reverse Recovery Charge918nCotes:00000		a. 78°C/W w	hen mounted on a	b. 156°	C/W when m	ounted on a	
rr       Reverse Recovery Time       IF = -4.9A, di/dt = 100A/ $\mu$ s       19       35       ns         Orr       Reverse Recovery Charge       IF = -4.9A, di/dt = 100A/ $\mu$ s       9       18       nC         otes:       Reverse Recovery design       9       18       nC         Reverse Recovery Charge       IF = -4.9A, di/dt = 100A/ $\mu$ s       9       18       nC         otes:       Reverse Recovery design.       9       18       nC         Reverse Recovery design.       IF = -4.9A, di/dt = 100A/ $\mu$ s       9       18       nC         otes:       Reverse Recovery design.       IF = -4.9A, di/dt = 100A/ $\mu$ s         If the user's board design.       IF = -4.9A, di/dt = 100A/ $\mu$ s         If the user's board design.       IF = -4.9A, di/dt = 100A/ $\mu$ s         If the user's board design.       IF = -4.9A, di/dt = 100A/ $\mu$ s         If the user's board design.       IF = -4.9A, di/dt = 100A/ $\mu$ s       IF = -4.9A, di		1 in <sup>2</sup> pad o		minir	num pad of 2	oz copper.	
$\begin{array}{ c c c c c c c c }\hline rr & Reverse Recovery Time & I_F = -4.9A, di/dt = 100A/\mu s & 19 & 35 & ns \\ \hline Q_{rr} & Reverse Recovery Charge & I_F = -4.9A, di/dt = 100A/\mu s & 9 & 18 & nC \\\hline otes: & & & \\ R_{0JA} \text{ is determined with the device mounted on a 1in2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC} is guaranteed by design while R_{0CA} is determined the user's board design. \hline \end{array}$							
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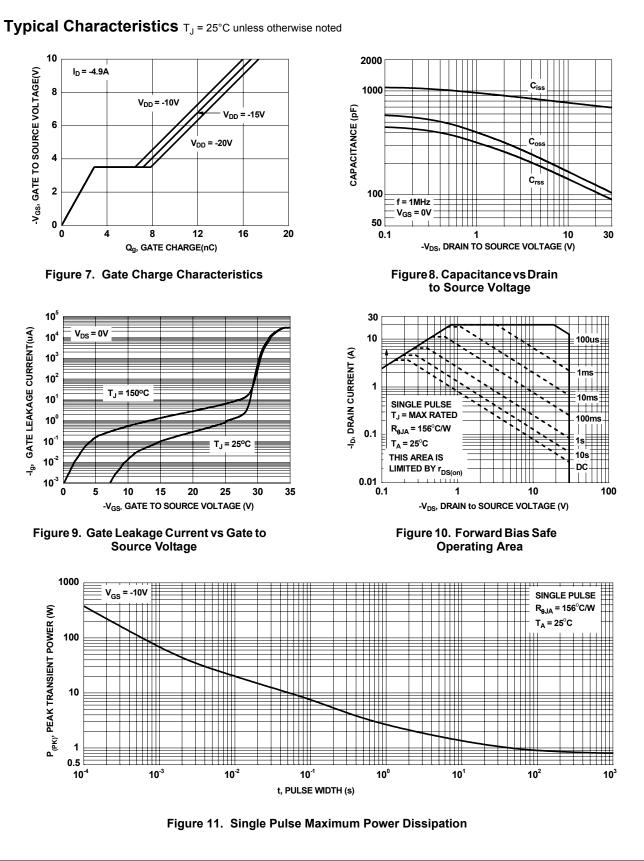
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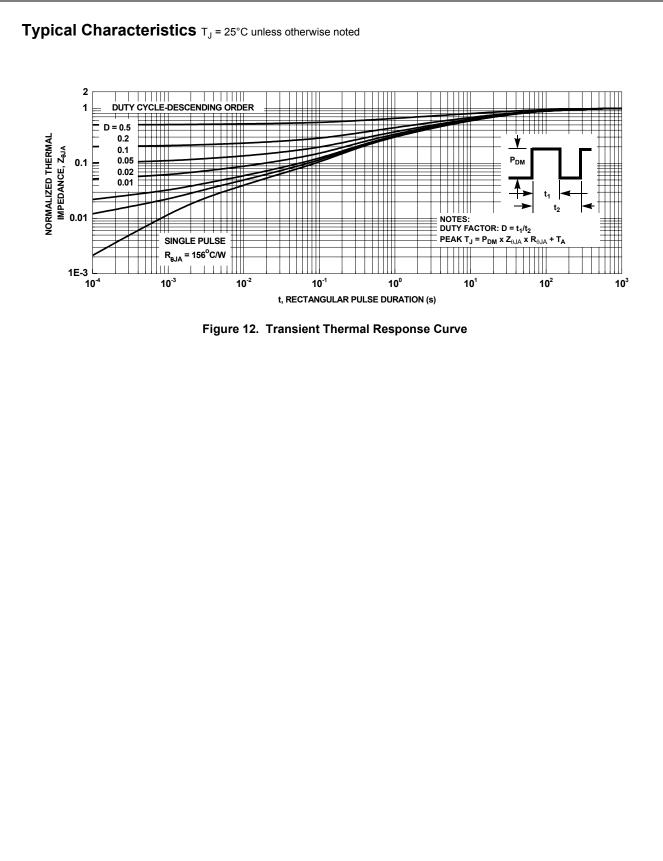
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